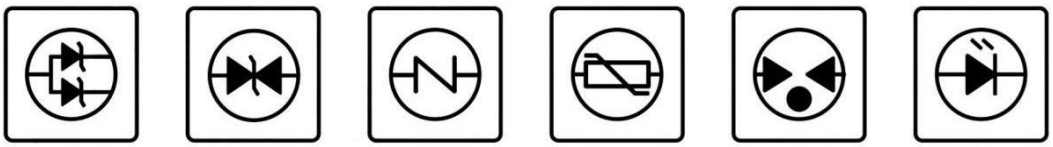
MSKSEMI 美森科
SEMICONDUCTOR



GBL6005-MS THRU GBL610-MS

Product specification

GBL6005-MS THRU GBL610-MS

REVERSE VOLTAGE - 50 to 1000 Volts
FORWARD CURRENT - 6.0 Amperes

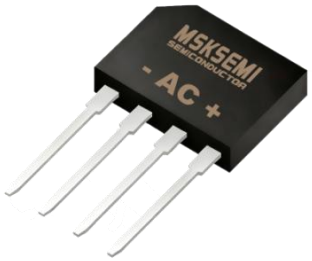
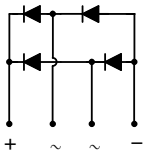
FEATURES

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 260 C/10 seconds at terminals

MECHANICAL DATA

- **Case** : Molded plastic body
- **Terminals** : Solder plated, solderable per MIL-STD-750,Method 2026
- **Polarity** : Polarity symbol marking on body
- **Mounting Position** : Any

REFERENCE NEWS

GBL



Marking

GBL6005-MS	GBL601-MS	GBL602-MS	GBL604-MS
MSKSEMI GBL6005 + AC -	MSKSEMI GBL601 + AC -	MSKSEMI GBL602 + AC -	MSKSEMI GBL604 + AC -
GBL606-MS	**GBL608-MS**	**GBL610-MS**	
MSKSEMI GBL606 + AC -	MSKSEMI GBL608 + AC -	MSKSEMI GBL610 + AC -	

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load, for capacitive load current derate by 20%.

Parameter		SYMBOLS	GBL6005 -MS	GBL601 -MS	GBL602 -MS	GBL604 -MS	GBL606 -MS	GBL608 -MS	GBL610 -MS	UNITS
Maximum repetitive peak reverse voltage		V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage		V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage		V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current with heatsink		$I_{(AV)}$	6.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load		I_{FSM}	125.0							A
Rating for fusing (t=8.3ms, Ta=25 C)		I^2t	93.4							A^2s
Maximum instantaneous forward voltage at 6.0A		V_F	1.10							V
Maximum DC reverse current at rated DC blocking voltage	T_A=25°C T_A=125°C	I_R	5.0 500							uA
Typical junction capacitance (Note 1)		C_J	42.0							pF
Typical thermal resistance		R_{qJA}	55.0							°C/W
Operating junction and storage temperature range		T_J,T_{STG}	-55 to +150							°C

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

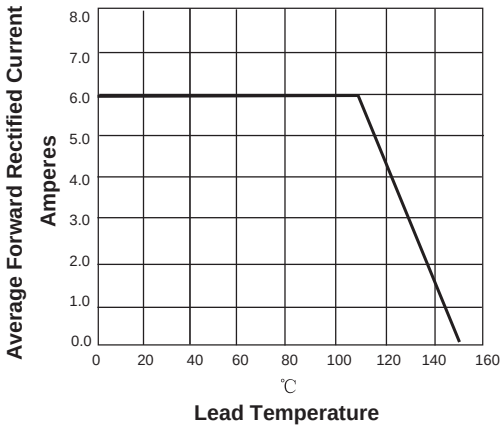


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

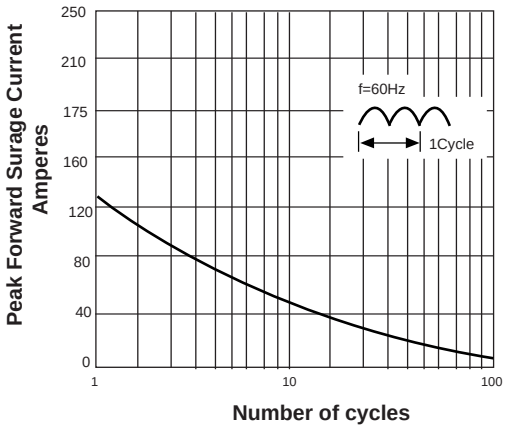


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

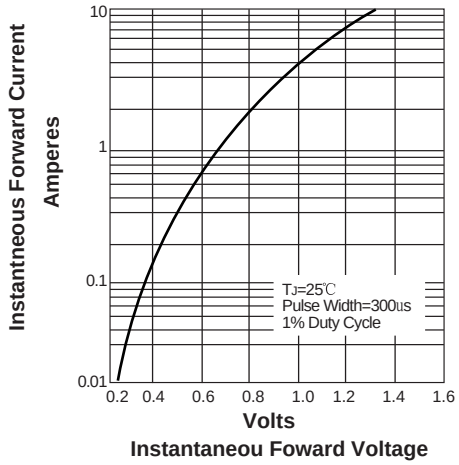
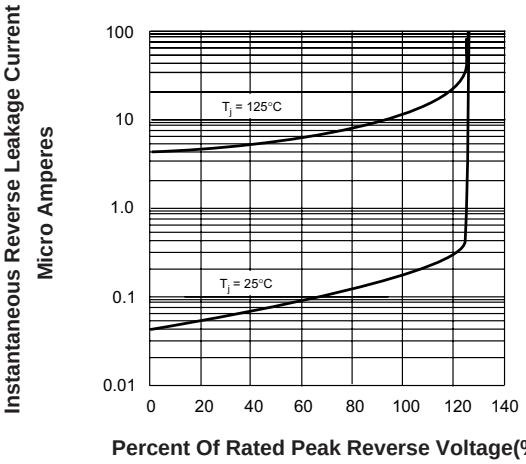
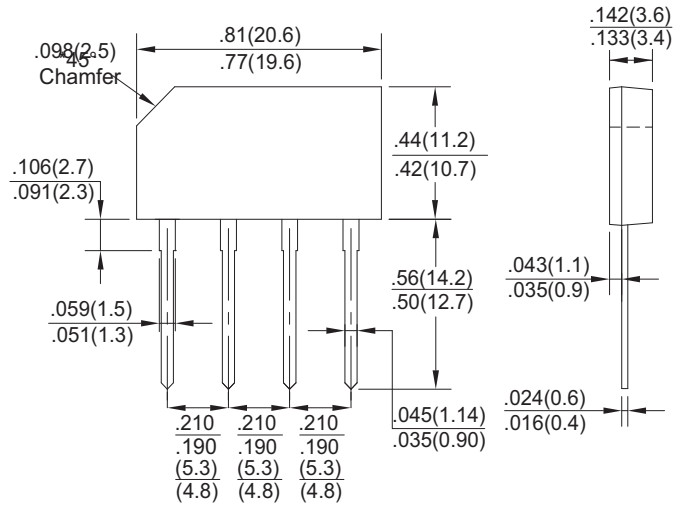


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



PACKAGE MECHANICAL DATA

GBL



Dimensions in inches and (milimeters)

REELSPECIFICATION

P/N	PKG	QTY
GBL6005-MS THRU GBL610-MS	GBL	500

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